IEEE P802.11
Wireless LANs

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| IEEE 802.11 TGbqTeleconference Minutes April 2025 |
| Date: 2025-04-08 |
| Author(s): |
| Name | Affiliation | Address | Phone | email |
| Jonghoe Koo | Samsung Electronics |  |  | jh89.koo@samsung.com |

Abstract

This document contains the IEEE 802.11 TGbq minutes for the teleconferences on April, 2025.

Revision history:

R0: initial version with the draft minutes for teleconference on 1 April 2025.

Abbreviations:

Q Question

A Answer

C Comment

# Tuesday, April 1 2025, 09:30am - 11:00am (EDT)

TGbq Chari: Edward Au (Huawei)

TGbq Vice-Chair: Rui Cao (NXP)

TGbq Vice-Chair: Abhishek Patil (Qualcomm)

TGbq Vice-Chair: Sang Kim (LG Electronics)

TGbq secretary: Jonghoe Koo (Samsung Electronics)

TGbq Editor: Cheng Chen (Intel)

**Opening formalities**

1. The IEEE 802.11 TGbq meeting was called to order at 09:30 EDT by the Chair.
2. Vice-chair Sang Kim introduced himself and sceratary Jonghoe Koo introduced himself.
3. Chair reminded the meeting registration.
4. Chair presented the TGbq meeting agenda [IEEE 802.11-25/0514r0](https://mentor.ieee.org/802.11/dcn/25/11-25-0514-00-00bq-april-2025-teleconference-agenda.xlsx) and reviewed the agenda items.
5. Chair reviewed the meeting agenda and the agenda was approved by unanimous consent.

**[Administrative items]**

1. Chair presented TGbq supplementary materials [IEEE 802.11-25/0417r0](https://mentor.ieee.org/802.11/dcn/25/11-25-0417-00-00bq-supplementary-material-for-march-2025-plenary.pptx) slides.
2. Chair reviewed IEEE 802 required notices (emphasizing to ensure to announce name and affiliation at the first time to speak, anti-trust compliance, IEEE 802 WG rules and policies, etc.), IEEE SA meeting guidelines, IEEE Codes of Ethics and Conduct, IEEE individual process, and IEEE-SA standards activities with the fair and equitable consideration.
3. Chair reminded all to record their attendance in IMAT and other meeting reminders.

**Contributions**

**Presentation of** [**IEEE 11-25/0363r0**](https://mentor.ieee.org/802.11/dcn/25/11-25-0363-00-00bq-channelization-in-immw.pptx)**, Channelization in IMMW (Yapu Li (OPPO))**

1. Yapu presented the contribution [IEEE 11-25/0363r0](https://mentor.ieee.org/802.11/dcn/25/11-25-0363-00-00bq-channelization-in-immw.pptx).
2. Q: The proposal, non-overlapped and non-aggregated channelization, is to define a new one rather than using the legacy channelization. How does the non-overlapping channelization make the IMMW signalling easier and what is the benefit of doing this?
3. A: We can reuse EHT or UHR PHY design where there are no overlapped channels except for 320 MHz channels. For 20, 40, 80, and 160 MHz, we have non-overlapped and non-aggregated channels. We can reuse this design for IMMW.
4. Q: Assuming that we consider the overlapped channelization, do we still consider the channel numbering that you proposed even to the non-overlapped channelization?
5. A: I think we can reuse the channel number. We may also need to define a preamble for IMMW 320 MHz
6. Q: Any thought about the scaling factor?
7. A: It needs further study since the scaling factor should be considered together with phase noise.

**Presentation of** [**IEEE 11-25/0365r0**](https://mentor.ieee.org/802.11/dcn/25/11-25-0365-00-00bq-ppdu-format-for-immw.pptx)**, PPDU Format for IMMW (Eunsung Park (LG Electronics))**

1. Eunsung presented the contribution [IEEE 11-25/0365r0](https://mentor.ieee.org/802.11/dcn/25/11-25-0365-00-00bq-ppdu-format-for-immw.pptx).
2. Q: In Slide 3, do you think we have to expand STF period, which incurs more processing time. AGC consumes one or several microseconds.
3. A: It is also one of the approaches to increase the length of the STF, though we need further discussion and investigation. It depends on a beamforming capability. If we use a directional antenna, in this case we may consider shorter than the omnidirectional case.
4. Q: In slide 4, you proposed a non-HT style. However, DCM and DUP mode have already been defined in sub 7 GHz. What is the benefit of the non-HT mode compared with the DUP mode and DCM? Furthermore, there are duplicate parts in EHT preamble. What is the benefit of introducing a different structure?
5. A: If there is no STF2 and LTF2, we have an advantage in terms of overhead. We can use this when the packet size is small.
6. Q: In slide 3, both two options are solely new designs. However, we have discussed to reuse EHT/UHR PPDUs for basic PPDU format.
7. A: We also consider reusing them. However, we may need longer STF or slightly modify them for IMMW.
8. Q: In slide3, do you think that 11a like PPDU can be applied to MIMO?
9. A: We can use 7 GHz to exchange side information. Though we use option 1 (11a like PPDU) for MIMO, it does not provide good efficiency so we may need to restrict other option for MIMO case.
10. C: Unified PPDU format is preferred.
11. Q: Do you consider a duplicate preamble structure for wider bandwidth case?
12. A: For both cases, STF, LTF, and SIG parts can be duplicate in the wider bandwidth where data part can be further optimized.
13. Q: In slide 6, you proposed a duplicate tone plan for the smallest bandwidth and proposed to allow separate PHYs to process each frequency sub-block. Is it aligned with ‘upclocking’ that we have discussed? Tone plans for 512-FFT and 1024-FFT are not duplicate with each other.
14. A: The intention was to use 80 MHz bandwidth case for the smallest bandwidth. However, we can determine the smallest bandwidth later based on the discussion.
15. Q: Is it the intention of your proposal that a tone plan for 512-FFT and another tone plan for 1024-FFT in wider bandwidth mode are duplicate?
16. A: If we assume to use 80 MHz as the smallest bandwidth, then we can use a duplicate tone plan as described in this proposal.
17. Q: For the data portion, a whole bandwidth is processed. Then what does it mean to process each frequency sub-block with separate PHYs?
18. A: We need further discussion later.
19. Q: Regarding the SIG, do you want to enable IMMW-SIG in addition to U-SIG? Alternatively, do you want to define a completely new design?
20. A: We need further discussion later. We think about L-SIG, too.
21. C: My preference is to remove L-SIG and, instead, to use a unified U-SIG for easier feature extension.
22. Q: We do not need L-SIG in my opinion. It is enough to define a new SIG format, e.g., U-SIG + xx-SIG.
23. A: I agree that we do not have to consider the backward compatibility.

**Closing formalities**

1. Chair announced that two MAC contributions are scheduled for presentation next week.
2. Chair called for PHY contributions.

**Adjourn (10:26am EDT)**

1. The chair announced that the call was adjourned at 10:26am EDT.

**List of Attendees**

TGbq 04/01/2025 Li, Haozheng TP-Link System Inc.

TGbq 04/01/2025 Zhou, Lei H3C Technologies Co., Limited

TGbq 04/01/2025 Li, Weiyi Spreadtrum Communication USA, Inc

TGbq 04/01/2025 Lee, Hong Won LG ELECTRONICS

TGbq 04/01/2025 Dong, Xiandong Xiaomi Communications Co., Ltd.

TGbq 04/01/2025 Luo, Chaoming Beijing OPPO telecommunications corp., ltd.

TGbq 04/01/2025 Wang, Zisheng ZTE Corporation

TGbq 04/01/2025 Sambasivan, Sam AT&T

TGbq 04/01/2025 Sadiq, Bilal Samsung Research America

TGbq 04/01/2025 Rosdahl, Jon Qualcomm Technologies, Inc.

TGbq 04/01/2025 Quan, Yingqiao Spreadtrum

TGbq 04/01/2025 Patwardhan, Gaurav Hewlett Packard Enterprise

TGbq 04/01/2025 Schelstraete, Sigurd MaxLinear

TGbq 04/01/2025 Patil, Abhishek Qualcomm Incorporated

TGbq 04/01/2025 Singh, Aditi Charter Communications

TGbq 04/01/2025 Park, Eunsung LG ELECTRONICS

TGbq 04/01/2025 Nayak, Peshal Samsung Research America

TGbq 04/01/2025 SUH, JUNG HOON Huawei Technologies Co., Ltd

TGbq 04/01/2025 McCann, Stephen Huawei Technologies Co., Ltd

TGbq 04/01/2025 Lin, Wei Xiaomi Communications Co., Ltd.

TGbq 04/01/2025 Li, Yapu Guangdong OPPO Mobile Telecommunications Corp....

TGbq 04/01/2025 Sun, Bo Sanechips

TGbq 04/01/2025 Li, Yanchun Huawei Technologies Co., Ltd

TGbq 04/01/2025 Koo, Jonghoe SAMSUNG ELECTRONICS

TGbq 04/01/2025 Zhong, Ke Ruijie Networks Co.,Ltd.

TGbq 04/01/2025 Choi, Jinsoo LG ELECTRONICS

TGbq 04/01/2025 Hussein, Abdalla Huawei Technologies Co., Ltd

TGbq 04/01/2025 Kim, Sang Gook LG ELECTRONICS

TGbq 04/01/2025 Gao, Ning Guangdong OPPO Mobile Telecommunications Corp....

TGbq 04/01/2025 Cha, Dongju LG ELECTRONICS

TGbq 04/01/2025 Hasabelnaby, Mahmoud Huawei Technologies Canada; Huawei Technologie...

TGbq 04/01/2025 Choi, JinHo SAMSUNG ELECTRONICS

TGbq 04/01/2025 Yano, Kazuto Advanced Telecommunications Research Institute...

TGbq 04/01/2025 Chen, Cheng Intel

TGbq 04/01/2025 Chen, Junbin TP-Link Systems Inc.

TGbq 04/01/2025 Kain, Carl Noblis, Inc.; USDoT

TGbq 04/01/2025 Chen, Wei-Han MediaTek Inc.

TGbq 04/01/2025 Cho, Hangyu LG ELECTRONICS

TGbq 04/01/2025 HUANG, CHIHAN MediaTek Inc.

TGbq 04/01/2025 CHENG, yajun Xiaomi Communications Co., Ltd.

TGbq 04/01/2025 Xiao, Tong Xiaomi Communications Co., Ltd.

TGbq 04/01/2025 Byeon, Seongho SAMSUNG ELECTRONICS

TGbq 04/01/2025 Au, Kwok Shum Huawei Technologies Co., Ltd

TGbq 04/01/2025 Chen, Xu Xiaomi Communications Co., Ltd.

TGbq 04/01/2025 Wei, Dong Guangdong OPPO Mobile Telecommunications Corp....

TGbq 04/01/2025 Xin, Yan Huawei Technologies Co., Ltd

TGbq 04/01/2025 Fan, Shuang Sanechips Technology Co., Ltd.

TGbq 04/01/2025 feng, Shuling MediaTek Inc.

TGbq 04/01/2025 Wee, Gaius Panasonic Holdings Corporation

TGbq 04/01/2025 Klein, Arik Huawei Technologies Co., Ltd

TGbq 04/01/2025 Kim, Youhan Qualcomm Technologies, Inc.

TGbq 04/01/2025 Zheng, Xiayu NXP Semiconductors

TGbq 04/01/2025 Deshmukh, Mrugen Ofinno

TGbq 04/01/2025 Fletcher, Paul Samsung Cambridge Solution Center

TGbq 04/01/2025 Cui, Yaoshen TP-Link Systems Inc.

TGbq 04/01/2025 Chou, Tzu-Hsuan Qualcomm Incorporated

TGbq 04/01/2025 Yamada, Ryota SHARP CORPORATION

TGbq 04/01/2025 Zhang, Jiayi Ofinno